ABSTRACT OF THE DISCLOSURE

Disclosed herein is a component supply method comprising the steps of sticking an adhesive sheet, which is provided on its upper surface with a first foam releasable adhesive layer whose adhesion is reduced by heating, onto an upper surface of a pallet having a side surface serving as a reference portion, sticking a wafer onto the upper surface of the adhesive sheet, cutting the wafer for obtaining a number of components, reducing the adhesion of the first adhesive layer by heating, and taking out the individual components, obtained by cutting the wafer, from the pallet. In the steps of sticking the adhesive sheet, sticking the wafer and taking out the components, the elements are located on the basis of the side surface of the pallet serving as a reference portion.

This Sheet Has Been Replaced

